

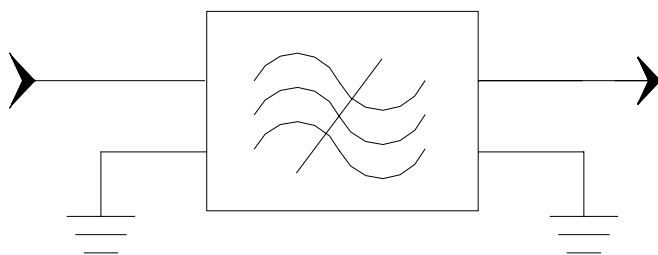
Specifications

Parameter	Unit	Minimum	Typical	Maximum
Center Frequency	MHz	159.9	160	160.1
Insertion Loss	dB		24.5	26
1 dB Bandwidth	MHz		14.75	
3 dB Bandwidth	MHz	15	15.19	
40 dB Bandwidth	MHz		16.5	16.6
Passband Variation	dB		0.8	1.1
Absolute Delay	usec		2.26	3
Ultimate Rejection	dB	48	50	
Substrate Material		YZ-LiNbO ₃		
Ambient Temperature	°C	25		
Package Size		DIP2212 (22.2x12.8x4.7mm ³)		

Notes:

1. All specifications are based on the test circuit shown
2. In production, devices will be tested at room temperature to a guardbanded specification to ensure electrical compliance over temperature
3. Electrical margin has been built into the design to account for the variations due to temperature drift and manufacturing tolerances
4. This is the optimum impedance in order to achieve the performance show

Matching Configuration



Source / Load Impedance=50 ohm

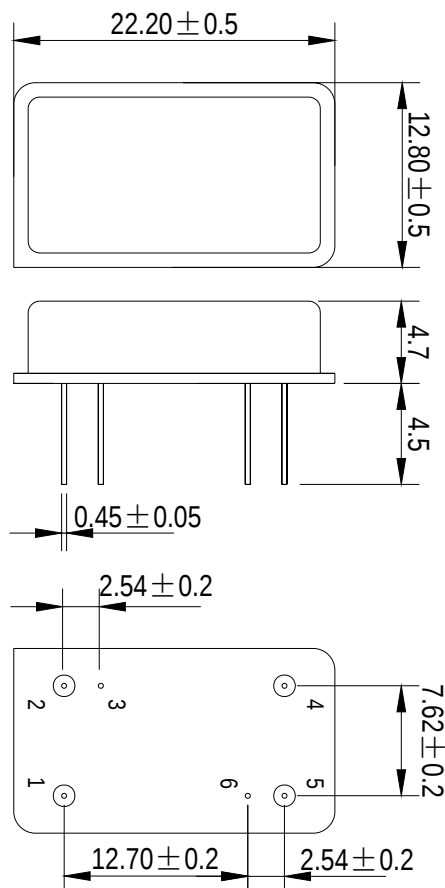
Notes - Component values may change depending
on board layout.



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Part Number	LBN16019		
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Package Dimension

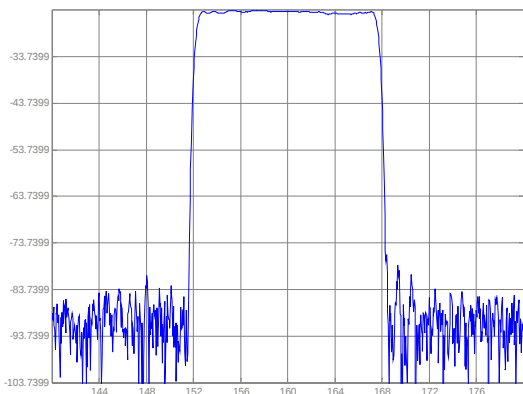


input: 1
Output: 5

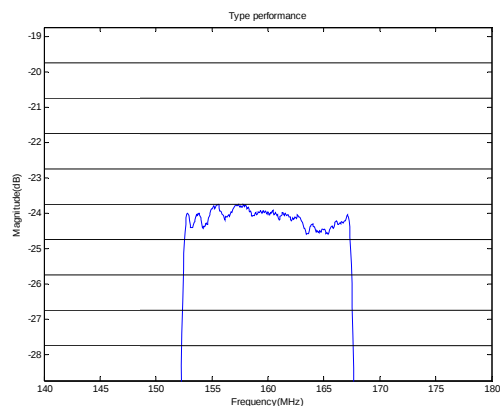
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Typical Performance

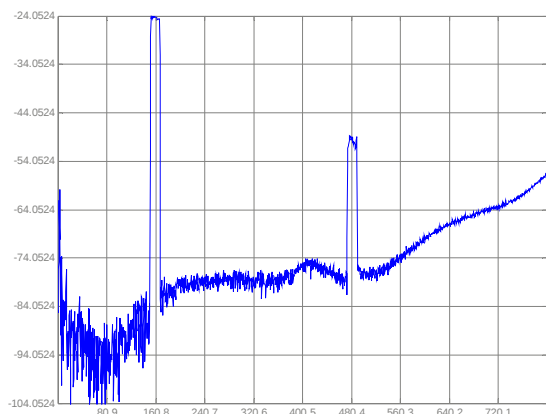
Frequency Respond



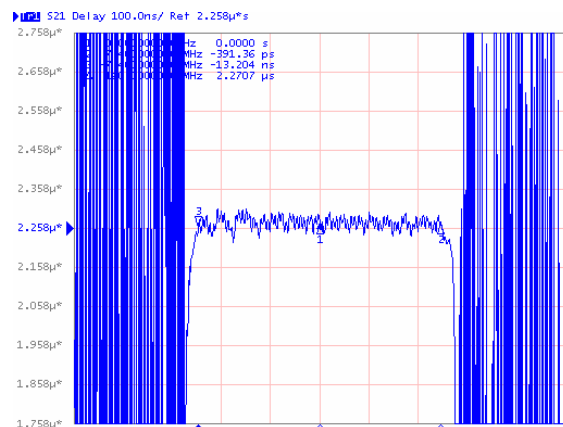
Passband Respond



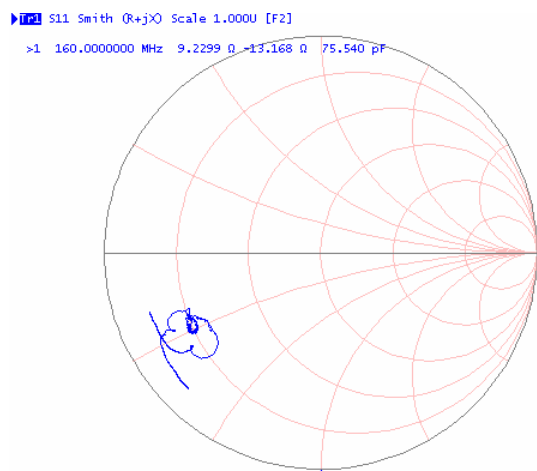
Wideband Respond



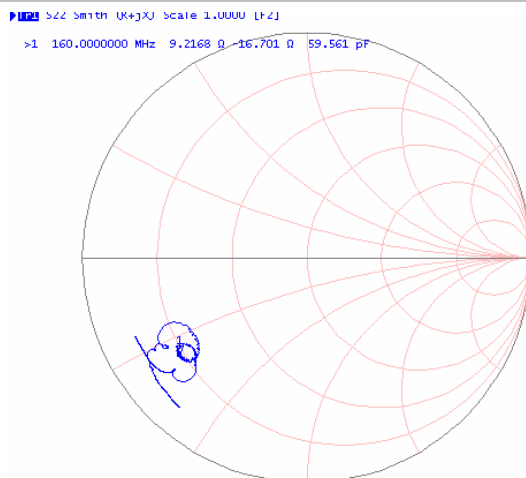
Group Delay Variation($f_0 \pm 7.4\text{MHz}$)



Simth Chart S11



Simth Chart S22



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